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# MT29F512G08CUCDBJ6-6R

## Data Sheets (2)

Data Sheet

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## Specs

## Orderable Parts for: MT29F512G08CUCDBJ6-6R



[SEE ALL 512GB MLC NAND PARTS](#)

	Status	Media	FBGA Code	SPD Data	Chipset Validation	PLP	Start Date	Alternative Part
MT29F512G08CUCDBJ6-6R:D	Production	N/A	NW561	N/A	N/A	No		N/A

## Detailed Specifications


Density	512Gb	Status	Production	RoHS	Yes	Width	x8
Voltage	3.3V	Package	LBGA	Pin Count	132-ball	MT/s	333 MT/s
I/O	Common	Product Name	FortisFlash				

## RoHS Certificates

Title & Description	Updated	Type	
<a href="#">RoHS Certificate of Compliance (PDF)</a>  Part-specific certification of how this product meets the requirements of the current DIRECTIVE 2002/95/EC, a.k.a. Restriction of Hazardous Substances (RoHS) Directive.	04/2015	RoHS Certification	<a href="#">ADD</a> <a href="#">EMAIL</a>
<a href="#">China RoHS Certificate (PDF)</a>  Part-specific certification as required by China's Management Methods for Controlling Pollution by Electronic Information Products.	04/2015	RoHS Certification	<a href="#">ADD</a> <a href="#">EMAIL</a>

# Documentation & Support

## Technical Note (50)

Title & Description	Updated	Type	
<p><b><a href="#">NAND Flash Controller on Spartan-3 (pdf)</a></b></p> <p>This technical note describes the Micron NAND Flash controller, techniques for interfacing the NAND Flash device with a processor and use of the Micron glueless interface to interface a processor with NAND Flash memory. (TN-29-06)</p>	07/2014	Technical Note	<a href="#">ADD</a> <a href="#">EMAIL</a>
<p><b><a href="#">Technical Note: Using Chip Enable Pin Reduction in NAND Flash Memory Devices (pdf)</a></b> </p> <p>This technical note describes how to enable and use the chip enable pin reduction feature in Micron's NAND Flash memory devices and discusses reduction limitations based on NAND package and system configuration. (TN-29-77)</p>	05/2014	Technical Note	<a href="#">ADD</a> <a href="#">EMAIL</a>
<p><b><a href="#">SEMI Wafer Map Format (pdf)</a></b></p> <p>Micron has adopted the wafer map file format approved by Semiconductor Equipment and Materials International (SEMI). With SEMI formatting, Micron's customers can be confident they will always receive consistent, compatible, reliable map files. (TN-00-21)</p>	03/2014	Technical Note	<a href="#">ADD</a> <a href="#">EMAIL</a>
<p><b><a href="#">Technical note: Using the Block Lock Feature on MT29F NAND Flash Memory Devices (pdf)</a></b></p> <p>This technical note describes the block lock feature on Micron's MT29F NAND Flash memory devices. (TN-2976)</p>	02/2014	Technical Note	<a href="#">ADD</a> <a href="#">EMAIL</a>
<p><b><a href="#">Enabling On-Die ECC NAND with JFFS2 (pdf)</a></b></p> <p>This technical note addresses altering the the MTD/NAND layer for the on-die ECC NAND device. (TN-29-75)</p>	08/2013	Technical Note	<a href="#">ADD</a> <a href="#">EMAIL</a>

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## Customer Service Note (5)

Title & Description	Updated	Type	
<p><b>Shipping Quantities (pdf)</b> Provides standard part quantities for shipping. (CSN-04)</p>	01/2015	Customer Service Note	<a href="#">ADD</a> <a href="#">EMAIL</a>
<p><b>Micron BGA Manufacturer's User Guide (pdf)</b> Provides information to enable customers to easily integrate both leading-edge and legacy Micron's ball grid array (BGA) packages into their manufacturing processes. It is intended as a set of high-level guidelines and a reference manual describing typical package-related and manufacturing process-flow practices. (CSN-33)</p>	12/2014	Customer Service Note	<a href="#">ADD</a> <a href="#">EMAIL</a>
<p><b>Micron Component and Module Packaging (pdf)</b> Explanation of Micron packaging labels and procedures. (CSN-16)</p>	11/2014	Customer Service Note	<a href="#">ADD</a> <a href="#">EMAIL</a>
<p><b>Product Marks/Product and Packaging Labels (pdf)</b> Explains product part marking, and product and packaging labels. (CSN-11)</p>	10/2014	Customer Service Note	<a href="#">ADD</a> <a href="#">EMAIL</a>
<p><b>PCN/EOL Systems (pdf)</b> Explains Micron's product change notification and end-of-life systems. (CSN-12)</p>	04/2012	Customer Service Note	<a href="#">ADD</a> <a href="#">EMAIL</a>

## Tool (6)

Title & Description	Updated	Type	
<p><b>FBGA Decoder</b> Micron's FBGA Part Marking Decoder makes it easier to understand part marking.</p>	12/2014	Tool	<a href="#">ADD</a> <a href="#">EMAIL</a>
<p><b>PISMO2 Boards (html)</b> The platform-independent storage module PISMO™ specifications provides a standard for convenient, interchangeable memory test boards. PISMO boards significantly reduce design inefficiencies, providing a huge benefit for the short development cycles of consumer products.</p>	10/2008	Tool	<a href="#">ADD</a> <a href="#">EMAIL</a>
<p><b>SLC, MLC, TLC – What's the Difference?</b> In this 4-minute, whiteboard video, Director of NAND Strategic Marketing, Kevin Kilbuck, provides a brief description of the technical differences among SLC, MLC, and TLC.</p>	01/0001	Tool	<a href="#">ADD</a> <a href="#">EMAIL</a>

### Choosing the Right NAND

Flash memory manufacturers are offering a variety of NAND Flash memory products—including some specialized NAND solutions—with significantly different performance capabilities and features across a number of process nodes. This NAND diversification means that designers cannot simply select any NAND Flash device for their applications, but rather need to have a basic understanding of the features and benefits of each type of NAND in order to select both the proper device and the proper supplier.

01/0001

Tool

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### ONFI Advantages

The Open NAND Flash Interface (ONFI) is a collaboration among Micron and many other NAND Flash suppliers, controller manufacturers, and designers. The primary goal of the ONFI working group is to develop open standards for the interface used to communicate with NAND Flash memory—standards that will increase compatibility and interoperability among conforming NAND devices from different vendors. This, in turn, will increase the supply base for standard devices, reduce design time, and speed time to market.

01/0001

Tool

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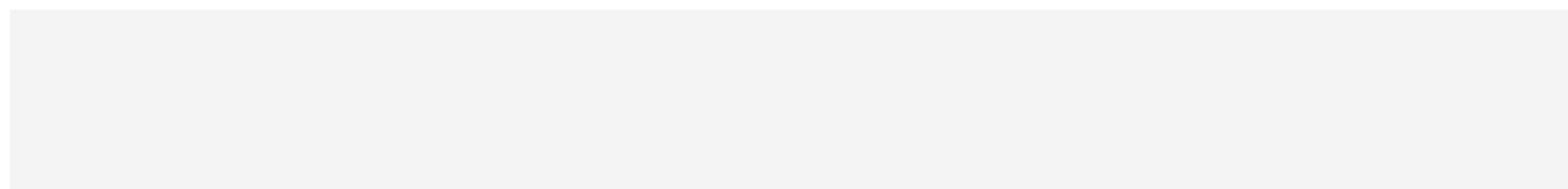
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## Parts with the same Data Sheet (6)

<del>MT29F512G08CUCDBJ6-6R</del> MT29F512G08CUCDBJ6-6R ( Current )	MT29F64G08CBCDBJ4-6R	MT29F128G08CECDBJ4-6R	MT29F192G08CGCDBG1-6R
<b>Production</b>	<b>Production</b>	<b>Production</b>	<b>Contact Factory</b>
<b>512Gb</b>	<b>64Gb</b>	<b>128Gb</b>	<b>64Gb</b>
<b>Yes</b>	Yes	Yes	Yes
<b>x8</b>	x8	x8	x8

<b>3.3V</b>	3.3V	3.3V	3.3V
<b>LBGA</b>	<b>VBGA</b>	<b>VBGA</b>	<b>VBGA</b>
<b>132-ball</b>	132-ball	132-ball	<b>272-ball</b>
<b>333 MT/s</b>	333 MT/s	333 MT/s	333 MT/s
<b>Common</b>	Common	Common	Common
<b>FortisFlash</b>	FortisFlash	FortisFlash	FortisFlash



## Where to Buy

### Orderable Parts

	Status	Media	FBGA Code	SPD Data	Chipset Validation	PLP	Start Date	Alternative Part
MT29F512G08CUCDBJ6-6R:D	Production	N/A	NW561	N/A	N/A	No		N/A

- OR -

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- Supercomputing Memory
- Ultrathin Solutions

### Memory and Storage Products

- DRAM
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- NAND Flash
- Managed NAND
- NOR Flash
- Hybrid Memory Cube
- Multichip Packages
- Solid State Drives

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